

12英寸全自动减薄设备

12 INCH FULLY-AUTOMATIC GRINDER

AG9500

● 最大有效加工尺寸 (mm)

Maximum effective product size (mm)

Ø8" ~ Ø12"

● 主轴配置方式

Configuration method of spindle

双主轴

Dual-spindle



• 特点 FEATURE

成熟稳定的加工过程。

Mature and stable processing.

IN-FEED主轴进给式磨削加工，加工精度高。

In-Feed spindle feed type High precision grinding.

全自动流程错误处理，异常快速复机。

Automatic Process Error Handling, Rapid Recovery from Abnormalities.

全自动上下料与传输定位，大大降低OP工作量。

Fully automatic loading and unloading with transfer positioning, greatly reducing OP workload.

便捷的操作与人机交互界面。

Convenient operation and human-machine interface.

多工位协同工作，加工效率高。

Multi-station collaborative work with high processing efficiency.

干进干出加工（DRY-IN & DRY-OUT），表面光洁。

Dry-in & Dry-Out processing, smooth surface.



• 功能 FUNCTION

注:「*」为选配功能,支持个性化定制
PS:「*」is an optional feature that can be customized by the customer

| 超薄晶圆加工与搬运传输

Ultra-thin wafer processing and transport

| 水、气二流体清洗

Water, gas two-fluid cleaning

| 操作日志记录

Operation log record

| 全自动/半自动模式

Fully Automatic/Semi-Automatic Mode

| 晶圆工作台自动清洗

Automatic wafer bench cleaning

| 功能模块化&软件定制

Functional modularity & software customization

| 8-12英寸晶圆兼容

8-12 inch wafer compatible

| 实时高精度接触式晶圆测厚

Real-time, high-precision contact wafer thickness measurement

| 真空预警与真空管路去水

Vacuum warning and vacuum line de-watering

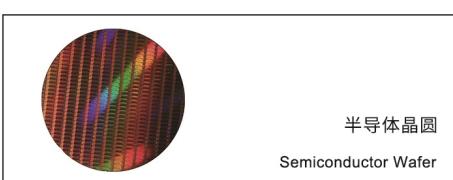
| 主轴水冷系统

Spindle water cooling system

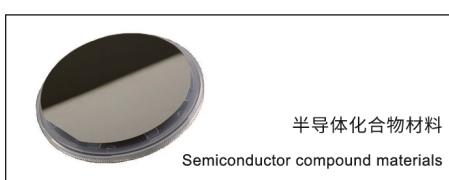
• 参数 PARAMETER

| | | |
|-----------------|---|--|
| 主轴转速 (Rpm) | Spindle speed (Rpm) | 1,000-4,000 |
| 真空吸台转速 (Rpm) | Vacuum suction table speed (Rpm) | 0-200 |
| Z轴最小位移量 (μm) | Minimum displacement of Z-axis (μm) | 0.1 |
| 最大磨削厚度 (mm) | Maximum grinding thickness (mm) | 1 |
| 晶片磨削厚度 (μm) | Wafer grinding thickness (μm) | ≥150 |
| 厚度变化量 (μm) | Amount of thickness change (μm) | ≤3 |
| 不同片之间厚度变化量 (μm) | Amount of thickness variation between different slices (μm) | ≤±5 |
| 精加工面粗糙度 | Roughness of finishing surface | Ras30nm(2000#)(该参数主要取决于磨轮) |
| 磨削方式 | Grinding method | 全自动主轴进给式磨削 Fully automatic spindle-feed grinding |
| 测高范围 (mm) | Height measurement range (mm) | 0 - 1 |
| 晶盒配置 | Crystalline box configuration | 2 |
| 设备重量 (kg) | Weight (kg) | ≈5,200 |
| 设备尺寸/W*D*H (mm) | Size / W*D*H (mm) | 1,500*3,150*1,900 |

• 应用 APPLICATION



半导体晶圆
Semiconductor Wafer



半导体化合物材料
Semiconductor compound materials



碳化硅
SiC